

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>	Docket Number (Optional) END920000094US1		Application Number
	Applicant(s) David J. Alcoe		
	Filing Date	Group Art Unit	

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		5,219,794	06/1993	Satoh et al.			
		5,311,402	05/1994	Kobayashi et al.			
		5,477,933	12/1995	Nguyen			
		5,894,410	04/1999	Barrow			
		5,759,737	06/1998	Feilchenfeld et al.			
		5,634,268	06/1997	Dalal et al.			

JC945 U.S. PTO
 09/714373
 11/16/99

FOREIGN PATENT DOCUMENTS

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

		Peterson et al., IBM Technical Disclosure Bulletin, "THERMALLY ENHANCED THREE-DIMENSIONAL FLEX INTERCONNECT OF MULTI-CHIP MODULES," Vol. 36, No. 12, December 1993, pg. 39

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

